Hex Type D Flip-Flop

The MC14174B hex type D flip-flop is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. Data on the D inputs which meets the setup time requirements is transferred to the Q outputs on the positive edge of the clock pulse. All six flip-flops share common clock and reset inputs. The reset is active low, and independent of the clock.

Features

- Static Operation
- All Inputs and Outputs Buffered
- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load Over the Rated Temperature Range
- Functional Equivalent to TTL 74174
- These Devices are Pb-Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Parameter	Symbol	Value	Unit
DC Supply Voltage Range	V _{DD}	-0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	V _{in} , V _{out}	–0.5 to V _{DD} + 0.5	V
Input or Output Current (DC or Transient) per Pin	I _{in} , I _{out}	±10	mA
Power Dissipation, per Package (Note 1)	PD	500	mW
Ambient Temperature Range	T _A	-55 to +125	°C
Storage Temperature Range		-65 to +150	°C
Lead Temperature (8-Second Soldering)		260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Temperature Derating: Plastic "P and D/DW"
 - Packages: 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, Vin and Vout should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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MARKING DIAGRAMS







= Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MC14174BCPG	PDIP-16 (Pb-Free)	500 Units/Rail
MC14174BDR2G	SOIC-16 (Pb-Free)	2500/Tape & Reel
NLV14174BDR2G	SOIC-16 (Pb-Free)	2500/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.













X = Don't Care



Figure 3. Timing Diagram



Figure 4. Functional Block Diagram

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

				- 5	– 55°C 25°C			125°C			
Characteristic		Symbol	V _{DD} Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage V _{in} = V _{DD} or 0	"0" Level	V _{OL}	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
$V_{in} = 0 \text{ or } V_{DD}$	"1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- -	Vdc
Input Voltage $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	"0" Level	V _{IL}	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V _{IH}	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11		Vdc
Output Drive Current (V_{OH} = 2.5 Vdc) (V_{OH} = 4.6 Vdc) (V_{OH} = 9.5 Vdc) (V_{OH} = 13.5 Vdc)	Source	I _{OH}	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	- - -	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	- - -	- 1.7 - 0.36 - 0.9 - 2.4	- - -	mAdc
(V _{OL} = 0.4 Vdc) (V _{OL} = 0.5 Vdc) (V _{OL} = 1.5 Vdc)	Sink	I _{OL}	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4		mAdc
Input Current		l _{in}	15	-	± 0.1	-	± 0.00001	± 0.1	-	± 1.0	μAdc
Input Capacitance, (V _{in} =	0)	C _{in}	-	-	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)		I _{DD}	5.0 10 15	- - -	5.0 10 20	- - -	0.005 0.010 0.015	5.0 10 20	- - -	150 300 600	μAdc
Total Supply Current (Note (Dynamic plus Quiesce Per Package) (C _L = 50 pF on all outp buffers switching)	ent,	Γ	5.0 10 15			$I_{T} = (2$	1.1 μΑ/kHz) f 2.3 μΑ/kHz) f 3.7 μΑ/kHz) f	+ I _{DD}			μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
The formulas given are for the typical characteristics only at 25°C.
To calculate total supply current at loads other than 50 pF: I_T(C_L) = I_T(50 pF) + (C_L - 50) Vfk where: I_T is in µA (per package), C_L in pF, V = (V_{DD} - V_{SS}) in volts, f in kHz is input frequency, and k = 0.003.

SWITCHING CHARACTERISTICS (Note 5) (C_L = 50 pF, T_A = 25° C)

			All Types			
Characteristic	Symbol	V _{DD} Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time t_{TLH} , $t_{THL} = (1.35 \text{ ns/pF}) C_L + 32 \text{ ns}$ t_{TLH} , $t_{THL} = (0.6 \text{ ns/pF}) C_L + 20 \text{ ns}$ t_{TLH} , $t_{THL} = (0.4 \text{ ns/pF}) C_L + 20 \text{ ns}$	t _{TLH} , t _{THL}	5.0 10 15	- - -	100 50 40	200 100 80	ns
Propagation Delay Time — Clock to Q t_{PLH} , t_{PHL} = (0.9 ns/pF) C _L + 165 ns t_{PLH} , t_{PHL} = (0.36 ns/pF) C _L + 64 ns t_{PLH} , t_{PHL} = (0.26 ns/pF) C _L + 52 ns	t _{PLH} , t _{PHL}	5.0 10 15	- - -	210 85 65	400 160 120	ns
Propagation Delay Time — Reset to Q $t_{PHL} = (0.9 \text{ ns/pF}) \text{ C}_{L} + 205 \text{ ns}$ $t_{PHL} = (0.36 \text{ ns/pF}) \text{ C}_{L} + 79 \text{ ns}$ $t_{PHL} = (0.26 \text{ ns/pF}) \text{ C}_{L} + 62 \text{ ns}$	^t PHL	5.0 10 15	- - -	250 100 75	500 200 150	ns
Clock Pulse Width	t _{WH}	5.0 10 15	150 90 70	75 45 35		ns
Reset Pulse Width	t _{WL}	5.0 10 15	200 100 80	100 50 40	- - -	ns
Clock Pulse Frequency	f _{cl}	5.0 10 15	- - -	7.0 12 15.5	2.0 5.0 6.5	mHz
Clock Pulse Rise and Fall Time	t _{TLH} , t _{THL}	5.0 10 15		- - -	15 5.0 4.0	μs
Data Setup Time	t _{su}	5.0 10 15	40 20 15	20 10 0	- - -	ns
Data Hold Time	t _h	5.0 10 15	80 40 30	40 20 15	- - -	ns
Reset Removal Time	t _{rem}	5.0 10 15	250 100 80	125 50 40	- - -	ns

The formulas given are for the typical characteristics only at 25°C.
Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

PACKAGE DIMENSIONS



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

i						
	MILLIN	IETERS	INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	9.80	10.00	0.386	0.393		
В	3.80	4.00	0.150	0.157		
C	1.35	1.75	0.054	0.068		
D	0.35	0.49	0.014	0.019		
F	0.40	1.25	0.016	0.049		
G	1.27	BSC	0.050 BSC			
J	0.19	0.25	0.008	0.009		
K	0.10	0.25	0.004	0.009		
М	0 °	7°	0 °	7°		
Ρ	5.80	6.20	0.229	0.244		
R	0.25	0.50	0.010	0.019		

SOLDERING FOOTPRINT



PACKAGE DIMENSIONS

PDIP-16 CASE 648-08 ISSUE T



NOTES:

- DIMENSIONING AND TOLERANCING PER 1.
- ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- 3.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH. 4.
- ROUNDED CORNERS OPTIONAL 5

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
К	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
М	0 °	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

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